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Kind regards,

Team Nexperia



# PMBT2907

40V, 600 mA, PNP switching transistor

6 March 2015

Product data sheet

## 1. General description

PNP switching transistor in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

NPN complement: PMBT2222

60V variant: PMBT2907A

## 2. Features and benefits

- Single general-purpose switching transistor
- AEC-Q101 qualified

## 3. Applications

- Switching and linear amplification

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	-40	V
$I_C$	collector current		-	-	-600	mA
$h_{FE}$	DC current gain	$V_{CE} = -10\text{ V}$ ; $I_C = -150\text{ mA}$ ; $T_{amb} = 25\text{ °C}$	100	-	300	

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	<p>TO-236AB (SOT23)</p>	<p>sym132</p>
2	E	emitter		
3	C	collector		



## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMBT2907	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

## 7. Marking

Table 4. Marking codes

Type number	Marking code <a href="#">[1]</a>
PMBT2907	%2B

[1] % = placeholder for manufacturing site code

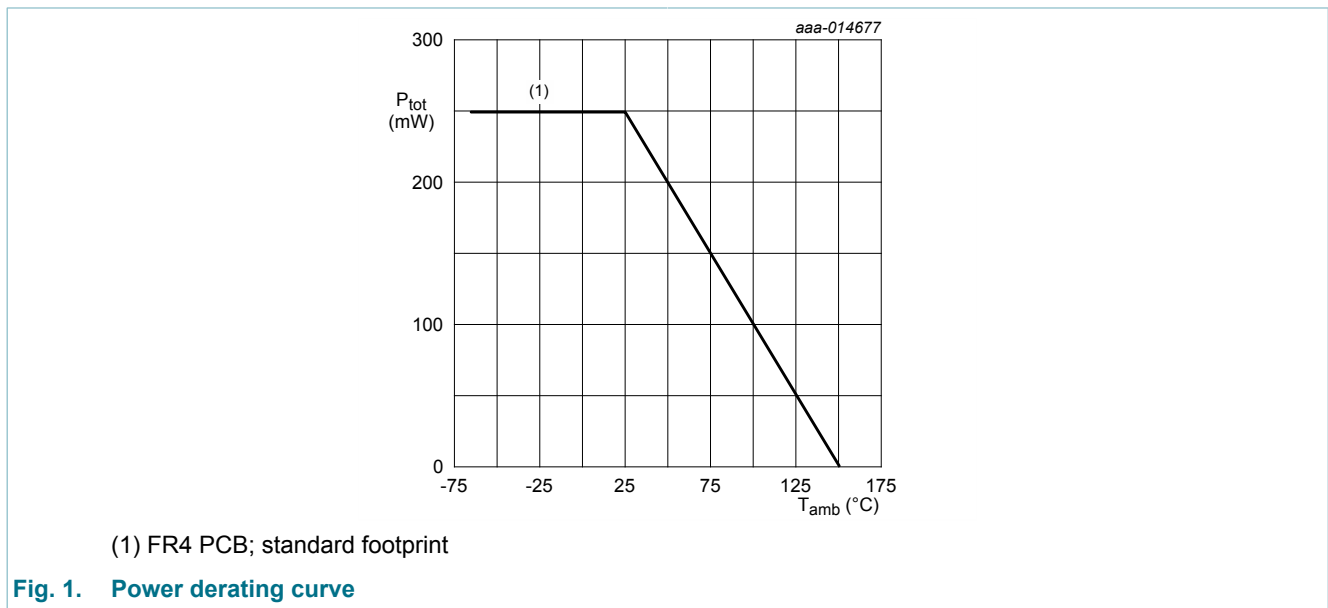
## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter		-	-60	V
$V_{CEO}$	collector-emitter voltage	open base		-	-40	V
$V_{EBO}$	emitter-base voltage	open collector		-	-5	V
$I_C$	collector current			-	-600	mA
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms		-	-800	mA
$I_{BM}$	peak base current			-	-200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	250	mW
$T_j$	junction temperature			-	150	°C
$T_{amb}$	ambient temperature			-65	150	°C
$T_{stg}$	storage temperature			-65	150	°C

[1] Transistor mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

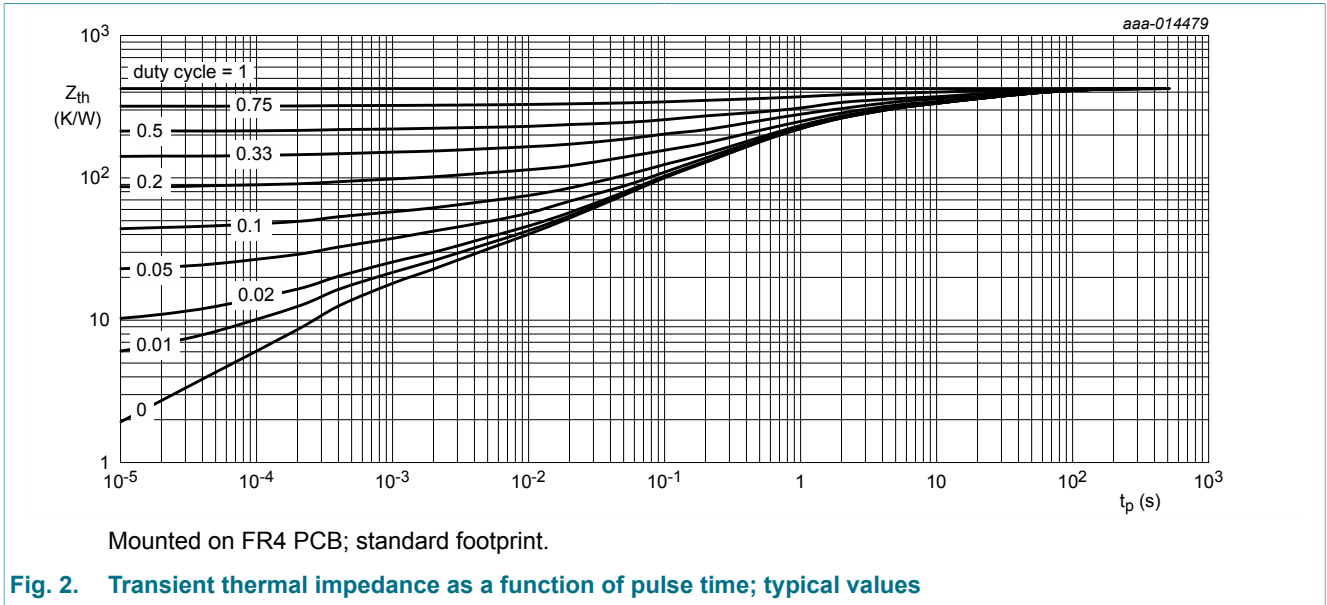


## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	500	K/W

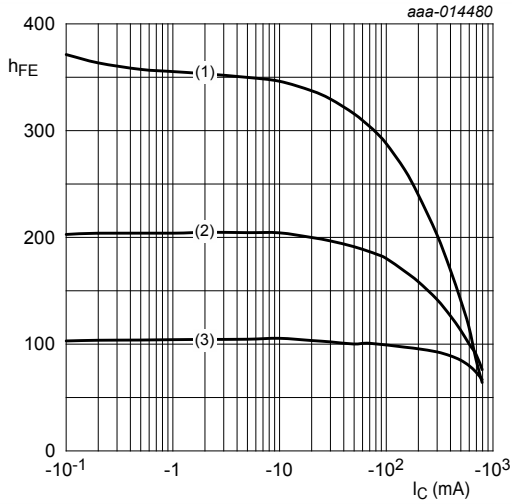
[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.



## 10. Characteristics

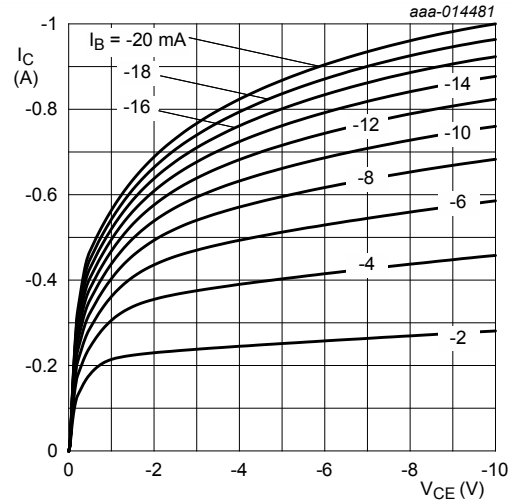
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = -50 V; I <sub>E</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-20	nA
		V <sub>CB</sub> = -50 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 125 °C	-	-	-20	μA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-50	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -10 V; I <sub>C</sub> = -0.1 mA; T <sub>amb</sub> = 25 °C	35	-	-	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -1 mA; T <sub>amb</sub> = 25 °C	50	-	-	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -10 mA; T <sub>amb</sub> = 25 °C	75	-	-	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -150 mA; T <sub>amb</sub> = 25 °C	100	-	300	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -500 mA; T <sub>amb</sub> = 25 °C	30	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = -150 mA; I <sub>B</sub> = -15 mA; T <sub>amb</sub> = 25 °C	-	-	-400	mV
		I <sub>C</sub> = -500 mA; I <sub>B</sub> = -50 mA; T <sub>amb</sub> = 25 °C	-	-	-1.6	V
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = -150 mA; I <sub>B</sub> = -15 mA; T <sub>amb</sub> = 25 °C	-	-	-1.3	V
		I <sub>C</sub> = -500 mA; I <sub>B</sub> = -50 mA; T <sub>amb</sub> = 25 °C	-	-	-2.6	V
t <sub>d</sub>	delay time	I <sub>C</sub> = -150 mA; I <sub>Bon</sub> = -15 mA; I <sub>Boff</sub> = 15 mA; T <sub>amb</sub> = 25 °C	-	-	12	ns
t <sub>r</sub>	rise time		-	-	30	ns
t <sub>on</sub>	turn-on time		-	-	40	ns
t <sub>s</sub>	storage time		-	-	300	ns
t <sub>f</sub>	fall time		-	-	65	ns
t <sub>off</sub>	turn-off time		-	-	365	ns
C <sub>C</sub>	collector capacitance		V <sub>CB</sub> = -10 V; I <sub>E</sub> = 0 A; i <sub>e</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	-	8
C <sub>E</sub>	emitter capacitance	V <sub>EB</sub> = -2 V; I <sub>C</sub> = 0 A; i <sub>c</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	-	30	pF
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = -20 V; I <sub>C</sub> = -50 mA; f = 100 MHz; T <sub>amb</sub> = 25 °C	200	-	-	MHz



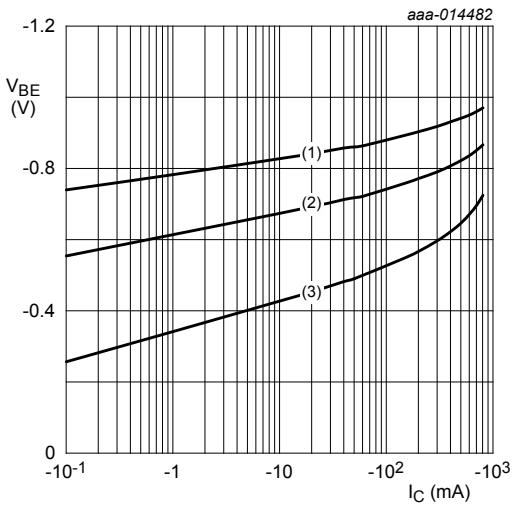
$V_{CE} = -10\text{ V}$   
 (1)  $T_{amb} = 150^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = -55^\circ\text{C}$

**Fig. 3. DC current gain as a function of collector current; typical values**



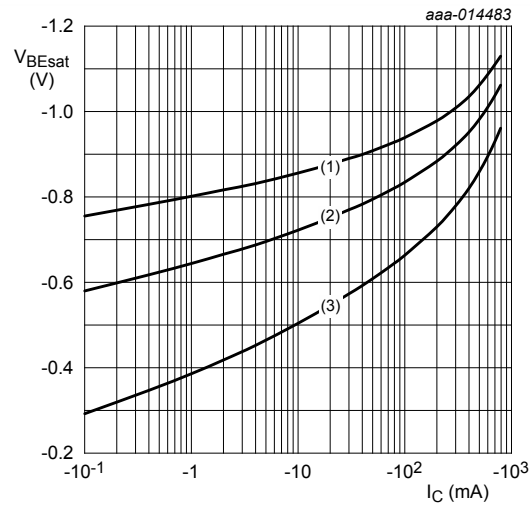
$T_{amb} = 25^\circ\text{C}$

**Fig. 4. Collector current as a function of collector-emitter voltage; typical values**



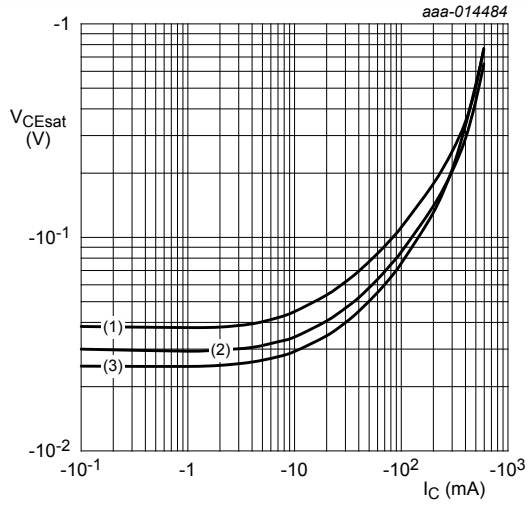
$V_{CE} = -10\text{ V}$   
 (1)  $T_{amb} = -55^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = 150^\circ\text{C}$

**Fig. 5. Base-emitter voltage as a function of collector current; typical values**



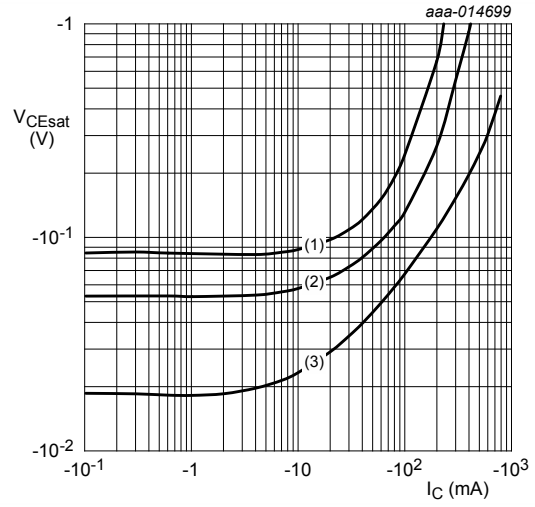
$I_C/I_B = 10$   
 (1)  $T_{amb} = -55^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = 150^\circ\text{C}$

**Fig. 6. Base-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = 150\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig. 7. Collector-emitter saturation voltage as a function of collector current; typical values**



$T_{amb} = 25\text{ °C}$   
 (1)  $I_C/I_B = 100$   
 (2)  $I_C/I_B = 50$   
 (3)  $I_C/I_B = 10$

**Fig. 8. Collector-emitter saturation voltage as a function of collector current; typical values**



### 11. Test information

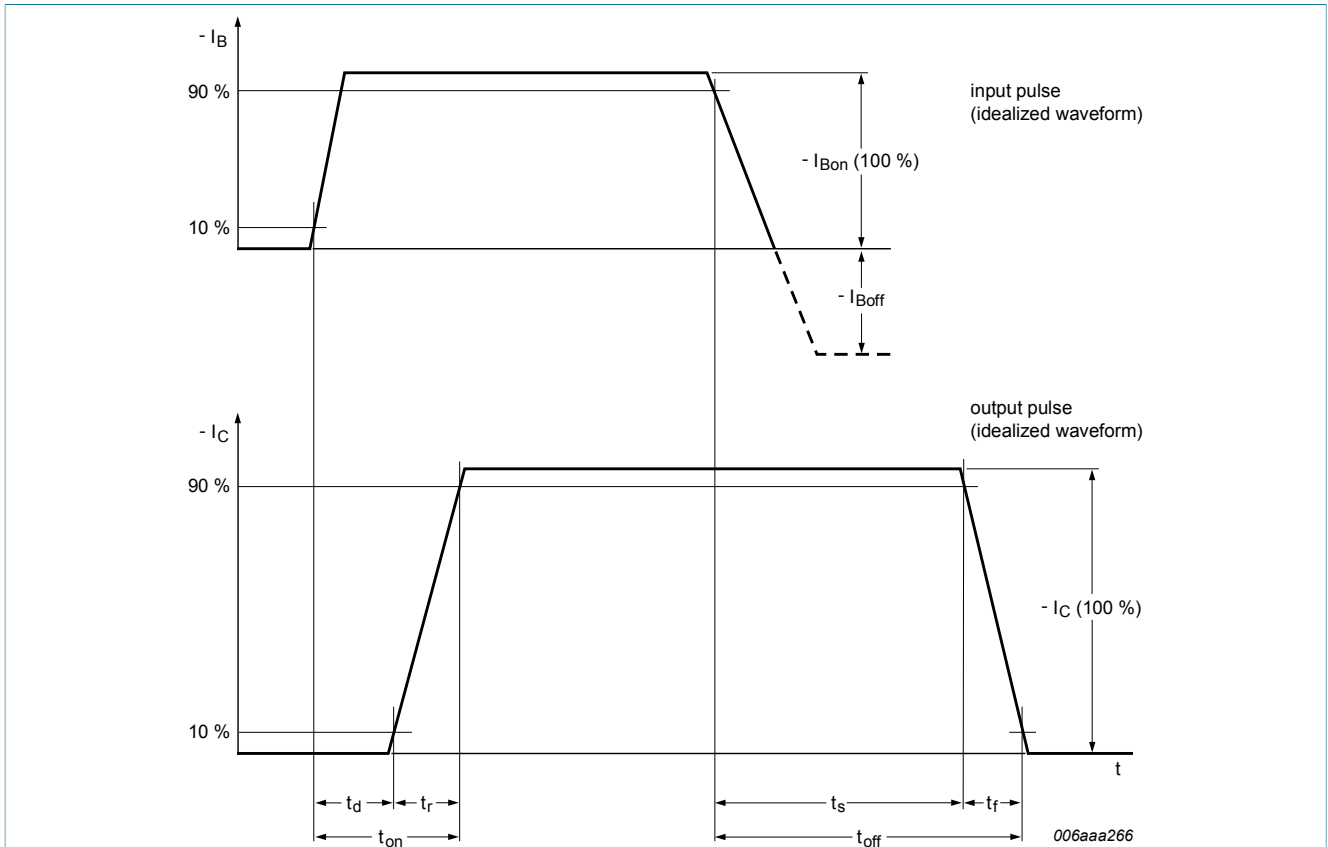


Fig. 9. BISS transistor switching time definition

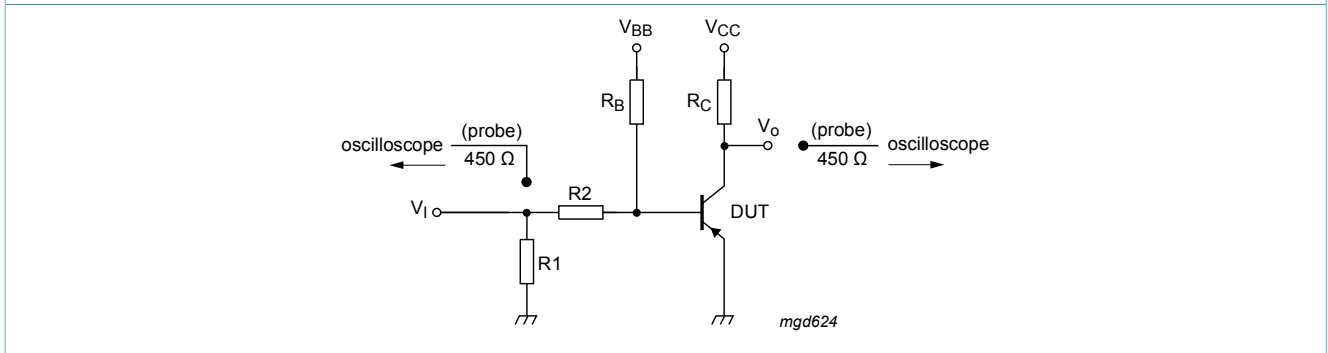


Fig. 10. Test circuit for switching times

#### 11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 12. Package outline

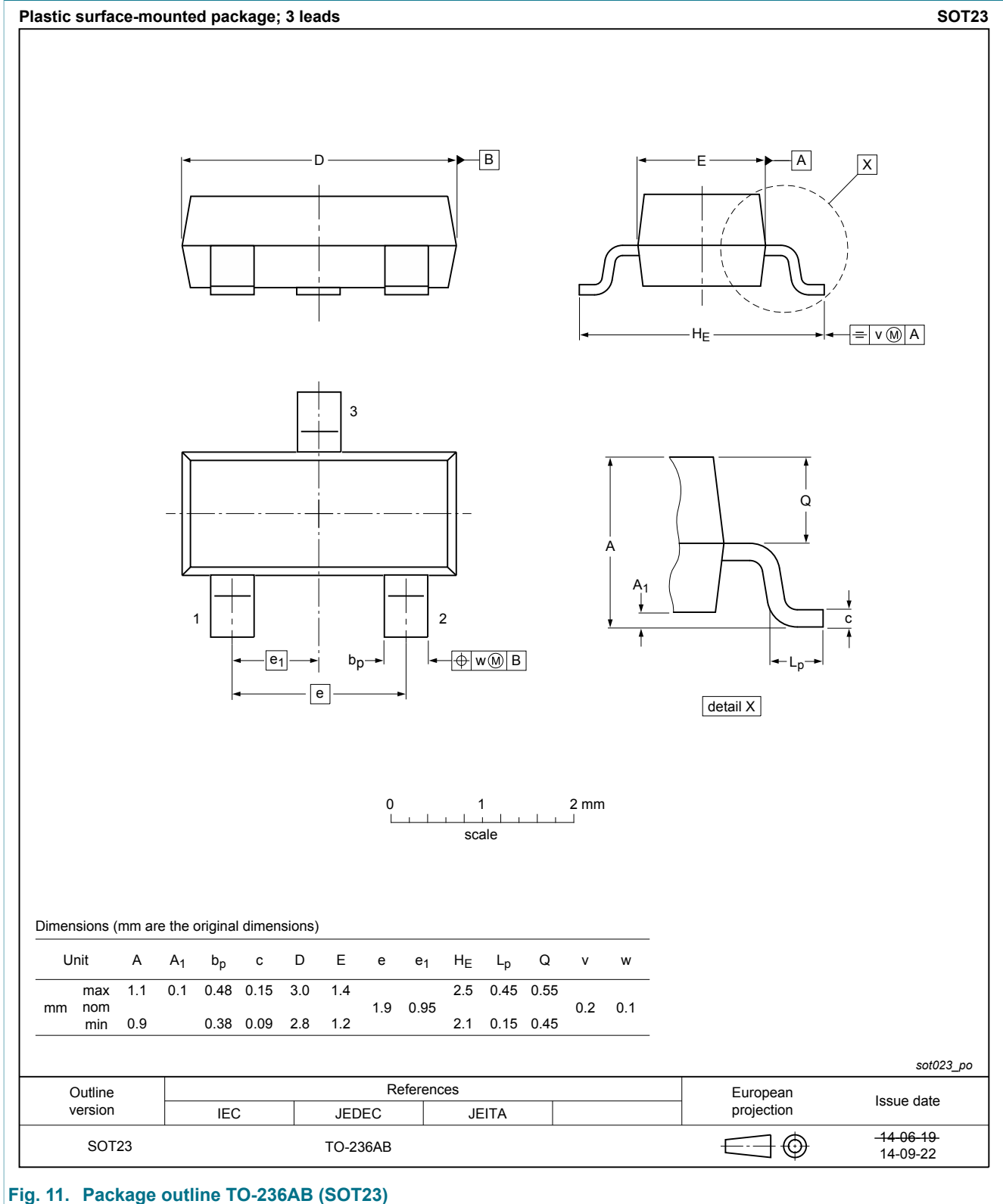


Fig. 11. Package outline TO-236AB (SOT23)

### 13. Soldering

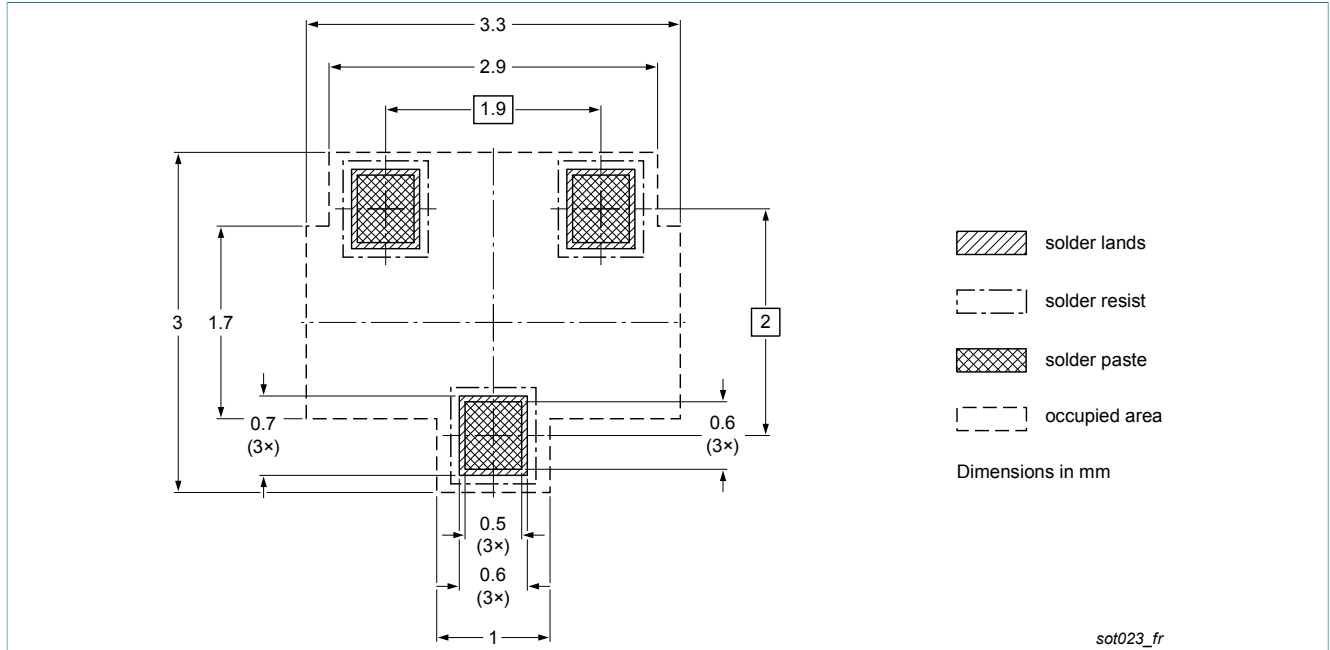


Fig. 12. Reflow soldering footprint for TO-236AB (SOT23)



Fig. 13. Wave soldering footprint for TO-236AB (SOT23)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMBT2907 v.5	20150306	Product data sheet	-	PMBT2907_ PMBT2907A v.4
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors</li> <li>Legal texts have been adapted to the new company name where appropriate</li> <li>Data sheet PMBT29007_PMBT2907A split into two separate data sheets</li> </ul>			
PMBT2907_ PMBT2907A v.4	20040116	Product data sheet	-	PMBT2907_ PMBT2907A v.3
PMBT2907_ PMBT2907A v.3	19990427	Product specification	-	PMBT2907_ PMBT2907A v.2
PMBT2907_ PMBT2907A v.2	19970904	Product specification	-	PMBT2907_ PMBT2907A v.1
PMBT2907_ PMBT2907A v.1	19970507	Product specification	-	-

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### 15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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